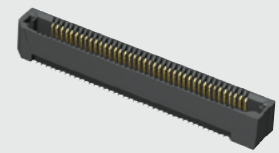
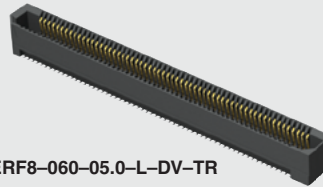


ERF8-020-05.0-S-DV-TR



ERF8-040-05.0-S-DV-TR



ERF8-060-05.0-L-DV-TR

**ERF8 SERIES**

**(0.80 mm) .0315"**

# RUGGED HIGH-SPEED SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?ERF8](http://www.samtec.com?ERF8)

**Insulator Material:**

Black LCP

**Contact Material:**

BeCu

**Plating:**

Au or Sn over 50 μ" (1.27 μm) Ni

**Current Rating:**

2.2 A per pin

(2 pins powered)

**Operating Temp Range:**

-55 °C to + 125 °C

**Voltage Rating:**

225 VAC / 318 VDC

**RoHS Compliant:**

Yes

**Board Mates:**

ERM8

**Cable Mates:**

ERCD, ERDP

Robust Edge Rate® contact improves "Zippered" unmating

10 to 200 I/Os



MATED HEIGHT*				
ERF8 LEAD STYLE	ERM8 LEAD STYLE			
	-02.0	-05.0	-08.0	-09.0
-05.0	(7.00) .276	(10.00) .394	(13.00) .512	(14.00) .551
-07.0	(9.00) .354	(12.00) .472	(15.00) .591	(16.00) .629
-09.0	(11.00) .453	(14.00) .551	(17.00) .669	(18.00) .709

\*Processing conditions will affect mated height.

**HIGH-SPEED CHANNEL PERFORMANCE**

ERM8/ERF8 @ 7 mm Mated Stack Height

Rating based on Samtec reference channel.

For full SI performance data visit [Samtec.com](http://Samtec.com) or contact [SLG@samtec.com](mailto:SLG@samtec.com)

**PAM 4**

**56** Gbps

**POWER/SIGNAL APPLICATION**

Compatible with UMP/TUMPS for flexible two-piece power/signal solutions

## PROCESSING

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

(0.10 mm) .004" max (005-030)

(0.12 mm) .005" max (040-060)\*

(0.15 mm) .006" max (070-100)\*

\*(.004" stencil solution may be available; contact [IPG@samtec.com](mailto:IPG@samtec.com))

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## PROTOCOLS

- 100 GbE
- PCI Express®

## ALSO AVAILABLE (MOQ Required)

- Mezzanine stack heights
- Contact Samtec.

## APPLICATIONS

STANDARD	POS.	PART NOs.	SERIES
NEXUS5001™.org POWER.org™	10	ASP-148421-01	ERF8-DV
	11	ASP-137969-01	ERF8-DV
	17	ASP-137973-01	ERF8-DV
ARM/HSSTP	20	ASP-130367-01	ERF8-DV
	23	ASP-130368-01	ERF8-DV
NEXUS5001™.org POWER.org™	25	ASP-148422-01	ERF8-DV
	35	ASP-135029-01	ERF8-DV
	40	ASP-148424-01	ERF8-DV

**Notes:**  
Patented

Some lengths, styles and options are non-standard, non-returnable.

ERF8	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	DV	OTHER OPTION	TR
	-005, -010, -011, -013, -020, -025, -030, -035, -040, -049, -050, -060, -070, -075	Specify LEAD STYLE from chart	-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail -S = 30 μ" (0.76 μm) Gold on contact, Matte Tin on tail	-L = Latching (Not available with -EGP or -EGPS option) -S = Extended Guide Post (Lead Style -07.0 only) (Not available with -L & -EGPS option) -EGPS = Extended Guide Post Shield (Lead Style -05.0 & -07.0 only) (Not available with -L & -EGP option) (-010, -020, -025, -030 only)	-K = (6.00 mm) .236" DIA Polyimide Film Pick & Place Pad	-TR = Tape & Reel Packaging (Not available with 100 positions)
	-100 (Available with -05.0 lead style only)	LEAD STYLE   A -05.0   (5.10) .200 07.0   (7.00) .276 -09.0   (9.00) .354				

Due to technical progress, all designs, specifications and components are subject to change without notice.